### Low Power Peak EMI Reducing Solution

### **Features**

- Generates an EMI optimized clock signal at the output.
- Integrated loop filter components.
- Operates with a 3.3 / 2.5V Supply.
- Operating current less than 4mA.
- Low power CMOS design.
- Input frequency range: 13MHz to 30MHz for 2.5V
  - : 13MHz to 30MHz for 3.3V
- Generates a 1X low EMI spread spectrum clock of the input frequency.
- Spread Spectrum Enable Control.
- Frequency deviation: ±1% @ 24MHz
- Available in 6-pin TSOT-23, 8-pin SOIC and 8-pin TSSOP packages.

### **Product Description**

The ASM3P2579A is a versatile spread spectrum frequency modulator designed specifically for a wide range of clock frequencies. The ASM3P2579A reduces electromagnetic interference (EMI) at the clock source, allowing system wide reduction of EMI of all clock dependent signals. The ASM3P2579A allows significant system cost savings by reducing the number of circuit board layers ferrite beads, shielding that are traditionally required to pass EMI regulations.

The ASM3P2579A uses the most efficient and optimized modulation profile approved by the FCC and is implemented by using a proprietary all digital method.

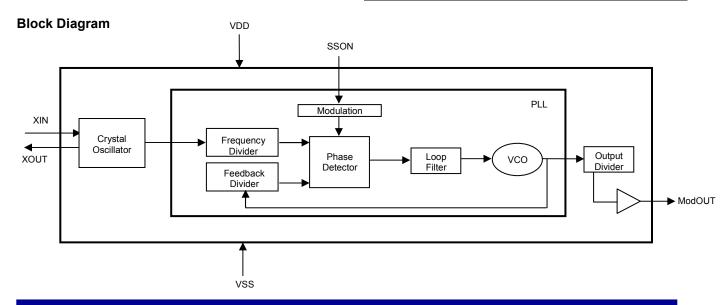
The ASM3P2579A modulates the output of a single PLL in order to "spread" the bandwidth of a synthesized clock, and more importantly, decreases the peak amplitudes of its harmonics. This results in significantly lower system EMI compared to the typical narrow band signal produced by oscillators and most frequency generators. Lowering EMI by increasing a signal's bandwidth is called 'spread spectrum clock generation'.

### **Applications**

The ASM3P2579A is targeted towards all portable devices with very low power requirements like MP3 players and digital still cameras.

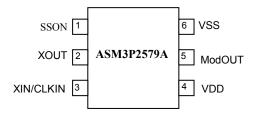
### **Key Specifications**

Description	Specification
Supply voltages	V <sub>DD</sub> = 3.3V/2.5V
Cycle-to-Cycle Jitter	200 pS (Max)
Output Duty Cycle	45/55% (worst case)
Modulation Rate Equation	F <sub>IN</sub> /640
Frequency Deviation	±1% @ 24MHz





# Pin Configuration (6-pin TSOT-23 Package)



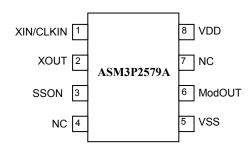
# **Pin Description**

Pin#	Pin Name	Type	Description				
1	SSON	I	When SSON is HIGH, the spread spectrum is enabled and when LOW, it turns off the spread spectrum. Connect the pin to ground When Spread Spectrum feature is not required.				
2	XOUT	0	Crystal connection. If using an external reference, this pin must be left unconnected.				
3	XIN/CLKIN	I	Crystal connection or external reference frequency input. This pin has dual functions. It can be connected either to an external crystal or an external reference clock.				
4	VDD	Р	Power supply for the entire chip				
5	ModOUT	0	Spread spectrum clock output.				
6	VSS	Р	Ground connection.				





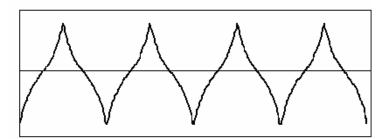
## Pin Configuration (8-pin SOIC and TSSOP Package)



# **Pin Description**

Pin#	Pin Name	Туре	Description
1	XIN/CLKIN	I	Crystal connection or external reference frequency input. This pin has dual functions. It can be connected either to an external crystal or an external reference clock.
2	XOUT	0	Crystal connection. If using an external reference, this pin must be left unconnected.
3	SSON	I	When SSON is HIGH, the spread spectrum is enabled and when LOW, it turns off the spread spectrum. Connect the pin to ground When Spread Spectrum feature is not required.
4	NC	-	No connect.
5	VSS	Р	Ground connection.
6	ModOUT	0	Spread spectrum clock output.
7	NC	_	No connect.
8	VDD	Р	Power supply for the entire chip

## **Modulation Profile**



## **Specifications**

Description	Specification
Frequency Range	13MHz < CLKIN < 30MHz
Modulation Equation	F <sub>IN</sub> /640
Frequency Deviation	±1% @ 24MHz



**Absolute Maximum Ratings** 

Symbol	Parameter	Rating	Unit
V <sub>DD</sub> , V <sub>IN</sub>	Voltage on any pin with respect to Ground	0.5 to +7.0	V
T <sub>STG</sub>	Storage temperature	-65 to +125	°C
T <sub>A</sub>	Operating temperature	0 to 70	°C
Ts	Max. Soldering Temperature (10 sec)	260	°C
$T_J$	Junction Temperature	150	°C
$T_DV$	Static Discharge Voltage (As per MIL-STD-883, Method 3015)	2	KV
Note: These are s device relia	tress ratings only and are not implied for functional use. Exposure to absolute maximum ratings for bility.	or prolonged periods of time r	nay affect

**DC Electrical Characteristics for 2.5V Supply** (Test condition: All parameters are measured at room temperature (+25°C) unless otherwise stated)

Symbol	Parameter	Min	Тур	Max	Unit
V <sub>IL</sub>	Input low voltage	GND - 0.3	_	0.8	V
V <sub>IH</sub>	Input high voltage	2.0	_	V <sub>DD</sub> + 0.3	V
I <sub>IL</sub>	Input low current	_	_	-35	μA
I <sub>IH</sub>	Input high current	_	-	35	μΑ
I <sub>XOL</sub>	XOUT output low current (@0.5V, V <sub>DD</sub> =2.5V)	_	3	_	mA
I <sub>XOH</sub>	XOUT output high current (@1.8V, V <sub>DD</sub> =2.5V)	_	3	_	mA
V <sub>OL</sub>	Output low voltage (V <sub>DD</sub> = 2.5 V, I <sub>OL</sub> = 8 mA)	_	-	0.6	V
V <sub>OH</sub>	Output high voltage (V <sub>DD</sub> = 2.5 V, I <sub>OH</sub> = 8 mA)	1.8	-	_	V
$I_{DD}$	Static supply current *	_	1.1	_	mA
I <sub>CC</sub>	Dynamic supply current (2.5V, 24MHz and no load)	_	3.5	_	mA
$V_{DD}$	Operating voltage	2.375	2.5	2.625	V
t <sub>ON</sub>	Power-up time (first locked cycle after power-up)	_	_	5	mS
Z <sub>OUT</sub>	Output impedance	_	50	_	Ω

AC Flectrical Characteristics for 2.5V Supply

Symbol	Parameter			Тур	Max	Unit
CLKIN	Input frequency		13	_	30	MHz
ModOUT	Output frequency		13	_	30	MHz
f.	Frequency Deviation	Input Frequency = 13MHz	_	_	±1.57	0/
f <sub>d</sub>	Input Frequency = 30MHz		_	_	±0.80	%
t <sub>LH</sub> *	Output rise time (measured fr	Output rise time (measured from 0.7V to 1.7V)			1.9	nS
t <sub>HL</sub> *	Output fall time (measured from	Output fall time (measured from 1.7V to 0.7V)			1.1	nS
t <sub>JC</sub>	Jitter (cycle to cycle)	_	_	200	pS	
t <sub>D</sub>	Output duty cycle		45	50	55	%
* t <sub>LH</sub> and t <sub>HL</sub> are n	neasured into a capacitive load of 15pF					



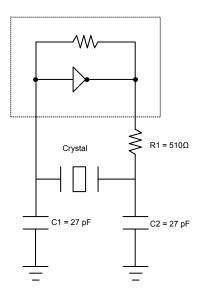
DC Electrical Characteristics for 3.3V Supply (Test condition: All parameters are measured at room temperature (+25°C) unless otherwise stated)

Symbol	Parameter	Min	Тур	Max	Unit
V <sub>IL</sub>	Input low voltage	GND - 0.3	-	0.8	V
V <sub>IH</sub>	Input high voltage	2.0	_	V <sub>DD</sub> + 0.3	V
I <sub>IL</sub>	Input low current	_	_	-35	μA
I <sub>IH</sub>	Input high current	_	_	35	μA
I <sub>XOL</sub>	XOUT output low current (@0.4V, V <sub>DD</sub> =3.3V)	_	3	_	mA
I <sub>XOH</sub>	XOUT output high current (@2.5V, V <sub>DD</sub> =3.3V)	_	3	_	mA
V <sub>OL</sub>	Output low voltage (V <sub>DD</sub> = 3.3 V, I <sub>OL</sub> = 8 mA)	_	_	0.4	V
V <sub>OH</sub>	Output high voltage (V <sub>DD</sub> = 3.3 V, I <sub>OH</sub> = 8 mA)	2.5	_	_	V
I <sub>DD</sub>	Static supply current*	_	1.2	_	mA
Icc	Dynamic supply current (3.3V, 24MHz and no load)	_	4.0	_	mA
$V_{DD}$	Operating voltage	2.7	3.3	3.6	V
t <sub>ON</sub>	Power-up time (first locked cycle after power-up)	_	_	5	mS
Z <sub>out</sub>	Output impedance	_	45	_	Ω

## **AC Electrical Characteristics for 3.3V Supply**

Symbol		Parameter			Max	Unit	
CLKIN	Input frequency		13	_	30	MHz	
ModOUT	Output frequency		13	_	30	MHz	
f.	Frequency Deviation	Input Frequency = 13MHz	_	_	±1.57	%	
f <sub>d</sub>	Frequency Deviation	Input Frequency = 30MHz	-	_	±0.80	70	
t <sub>LH</sub> *	Output rise time (meas	Output rise time (measured from 0.8 to 2.0V)			1.7	nS	
t <sub>HL</sub> *	Output fall time (measu	ired at 2.0V to 0.8V)	0.4	1.0	1.2	nS	
t <sub>JC</sub>	Jitter (cycle to cycle)	Jitter (cycle to cycle)		_	200	pS	
t <sub>D</sub>	Output duty cycle	Output duty cycle			55	%	
${}^{*}t_{LH}$ and $t_{HL}$ are measured into	*t <sub>I H</sub> and t <sub>HI</sub> are measured into a capacitive load of 15pF						

# **Typical Crystal Oscillator Circuit**



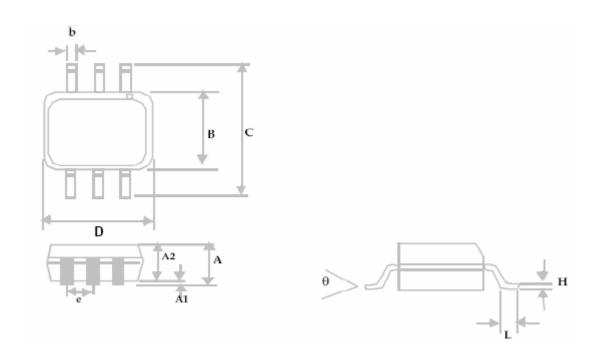
# **Typical Crystal Specifications**

Fundamental AT cut parallel resonant crystal				
Nominal frequency	14.31818 MHz			
Frequency tolerance	± 50 ppm or better at 25°C			
Operating temperature range	-25°C to +85°C			
Storage temperature	-40°C to +85°C			
Load capacitance	18pF			
Shunt capacitance	7pF maximum			
ESR	25 Ω			



# **Package Information**

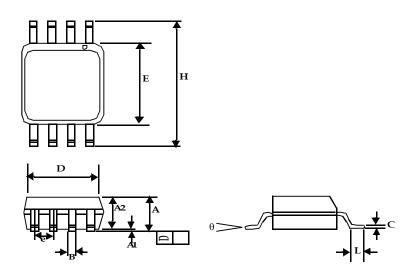
# 6-pin TSOT-23 Package



	Dimensions				
Symbol	Inc	hes	Millimeters		
	Min	Max	Min	Max	
Α		0.04		1.00	
A1	0.00	0.004	0.00	0.10	
A2	0.033	0.036	0.84	0.90	
b	0.012	0.02	0.30	0.50	
Н	0.005	BSC	0.127 BSC		
D	0.114	BSC	2.90 BSC		
В	0.06	BSC	1.60 BSC		
е	0.0374	4 BSC	0.950 BSC		
С	0.11 BSC		2.80	BSC	
L	0.0118	0.02	0.30	0.50	
θ	0°	4°	0°	4°	



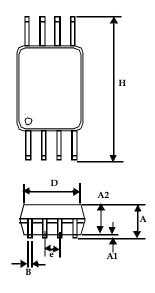
# 8-Pin SOIC Package

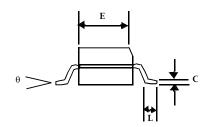


	Dimensions				
Symbol	Inc	hes	Millimeters		
	Min	Max	Min	Max	
A1	0.004	0.010	0.10	0.25	
Α	0.053	0.069	1.35	1.75	
A2	0.049	0.059	1.25	1.50	
В	0.012	0.020	0.31	0.51	
С	0.007	0.010	0.18	0.25	
D	0.193	BSC	4.90	BSC	
Е	0.154	BSC	3.91	BSC	
е	0.050	BSC	1.27	BSC	
Н	0.236 BSC		6.00	BSC	
L	0.016	0.050	0.41	1.27	
θ	0°	8°	0°	8°	



# 8-Pin TSSOP Package





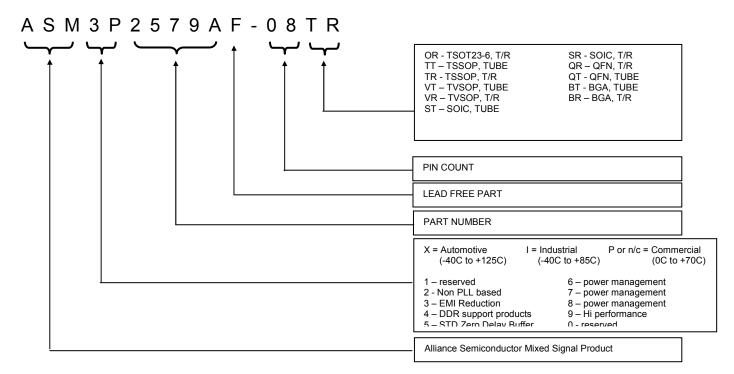
	Dimensions			
Symbol	Inches		Millimeters	
	Min	Max	Min	Max
Α		0.043		1.10
A1	0.002	0.006	0.05	0.15
A2	0.033	0.037	0.85	0.95
В	0.008	0.012	0.19	0.30
С	0.004	0.008	0.09	0.20
D	0.114	0.122	2.90	3.10
Е	0.169	0.177	4.30	4.50
е	0.026 BSC		0.65 BSC	
Н	0.252 BSC		6.40 BSC	
L	0.020	0.028	0.50	0.70
θ	0°	8°	0°	8°



## **Ordering Information**

Part Number	Marking	Package Type	Temperature
ASM3P2579AF-06OR	S4LL	6-Pin TSOT-23, TAPE & REEL	Commercial
ASM3P2579AF-08TT	ASM3P2579AFT	8-Pin TSSOP, TUBE	Commercial
ASM3P2579AF-08TR	ASM3P2579AFT	8-Pin TSSOP, TAPE & REEL	Commercial
ASM3P2579AF-08ST	ASM3P2579AFS	8-Pin SOIC, TUBE	Commercial
ASM3P2579AF-08SR	ASM3P2579AFS	8-Pin SOIC, TAPE & REEL	Commercial
ASM3P2579A-06OR	S1LL	6-Pin TSOT-23, TAPE & REEL	Commercial
ASM3P2579A-08TT	ASM3P2579AT	8-Pin TSSOP, TUBE	Commercial
ASM3P2579A-08TR	ASM3P2579AT	8-Pin TSSOP, TAPE & REEL	Commercial
ASM3P2579A-08ST	ASM3P2579AS	8-Pin SOIC, TUBE	Commercial
ASM3P2579A-08SR	ASM3P2579AS	8-Pin SOIC, TAPE & REEL	Commercial

## **Device Ordering Information**



Licensed under U.S Patent Nos 5,488,627 and 5,631,921



Alliance Semiconductor Corporation 2595, Augustine Drive, Santa Clara, CA 95054 Tel# 408-855-4900 Fax: 408-855-4999 www.alsc.com Copyright © Alliance Semiconductor All Rights Reserved Preliminary Information Part Number: ASM3P2579A Document Version: v0.3

Note: This product utilizes US Patent # 6,646,463 Impedance Emulator Patent issued to Alliance Semiconductor, dated 11-11-2003

© Copyright 2003 Alliance Semiconductor Corporation. All rights reserved. Our three-point logo, our name and Intelliwatt are trademarks or registered trademarks of Alliance. All other brand and product names may be the trademarks of their respective companies. Alliance reserves the right to make changes to this document and its products at any time without notice. Alliance assumes no responsibility for any errors that may appear in this document. The data contained herein represents Alliance's best data and/or estimates at the time of issuance. Alliance reserves the right to change or correct this data at any time, without notice. If the product described herein is under development, significant changes to these specifications are possible. The information in this product data sheet is intended to be general descriptive information for potential customers and users. and is not intended to operate as, or provide, any quarantee or warrantee to any user or customer. Alliance does not assume any responsibility or liability arising out of the application or use of any product described herein, and disclaims any express or implied warranties related to the sale and/or use of Alliance products including liability or warranties related to fitness for a particular purpose, merchantability, or infringement of any intellectual property rights, except as express agreed to in Alliance's Terms and Conditions of Sale (which are available from Alliance). All sales of Alliance products are made exclusively according to Alliance's Terms and Conditions of Sale. The purchase of products from Alliance does not convey a license under any patent rights, copyrights; mask works rights, trademarks, or any other intellectual property rights of Alliance or third parties. Alliance does not authorize its products for use as critical components in life-supporting systems where a malfunction or failure may reasonably be expected to result in significant injury to the user, and the inclusion of Alliance products in such life-supporting systems implies that the manufacturer assumes all risk of such use and agrees to indemnify Alliance against all claims arising from such use.